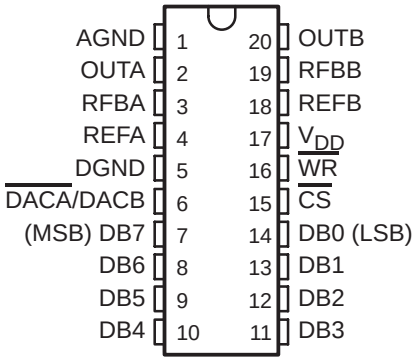
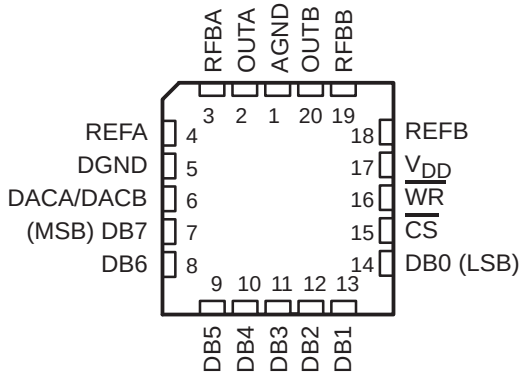
- **Easily Interfaced to Microprocessors**
- **On-Chip Data Latches**
- **Monotonic Over the Entire A/D Conversion Range**
- **Interchangeable With Analog Devices AD7528 and PMI PM-7528**
- **Fast Control Signaling for Digital Signal Processor (DSP) Applications Including Interface With TMS320**
- **Voltage-Mode Operation**
- **CMOS Technology**

KEY PERFORMANCE SPECIFICATIONS	
Resolution	8 bits
Linearity Error	1/2LSB
Power Dissipation at V_{DD} = 5V	20mW
Settling Time at V_{DD} = 5V	100ns
Propagation Delay Time at V_{DD} = 5V	80ns

DW, N OR PW PACKAGE
(TOP VIEW)



FN PACKAGE
(TOP VIEW)



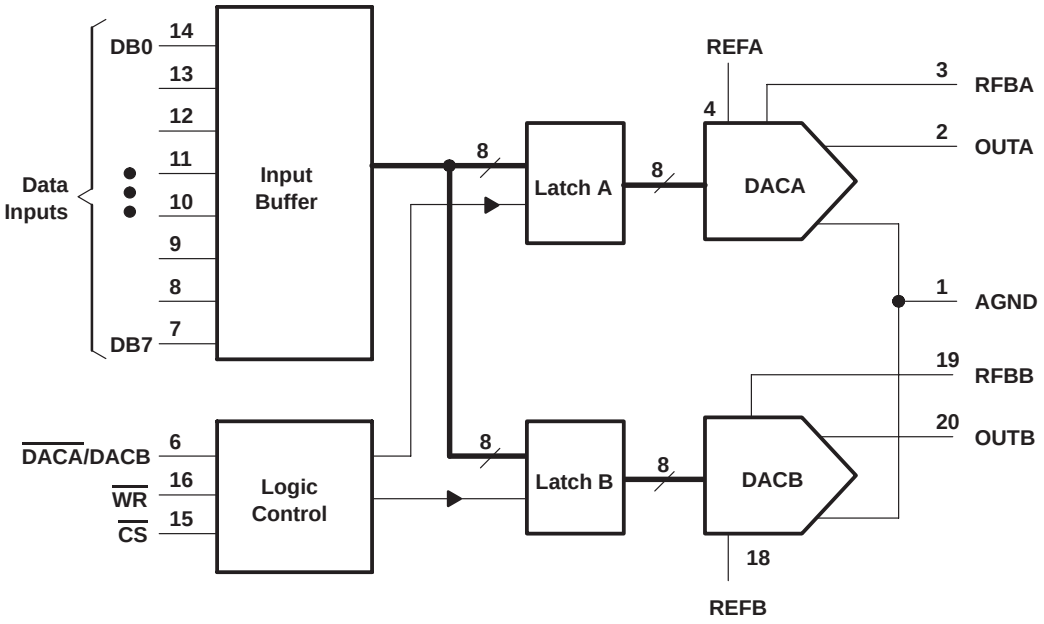
description

The TLC7528C, TLC7528E, and TLC7528I are dual, 8-bit, digital-to-analog converters (DACs) designed with separate on-chip data latches and feature exceptionally close DAC-to-DAC matching. Data are transferred to either of the two DAC data latches through a common, 8-bit, input port. Control input $\overline{\text{DACA}}$/DACB determines which DAC is to be loaded. The load cycle of these devices is similar to the write cycle of a random-access memory, allowing easy interface to most popular microprocessor buses and output ports. Segmenting the high-order bits minimizes glitches during changes in the most significant bits, where glitch impulse is typically the strongest.

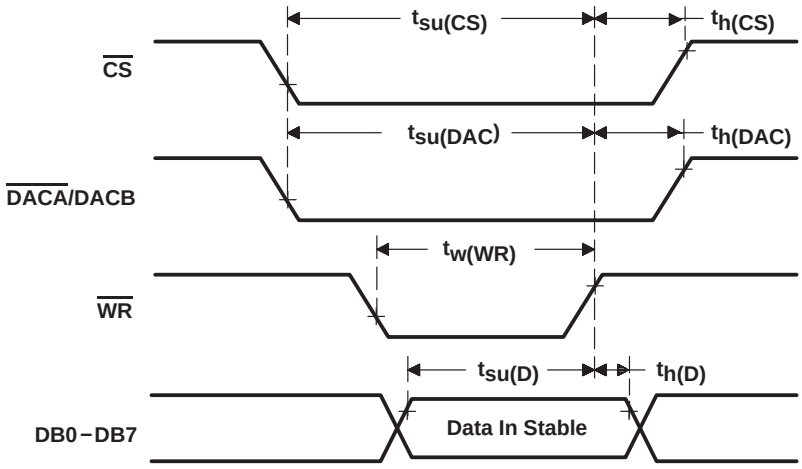
These devices operate from a 5V to 15V power supply and dissipates less than 15mW (typical). The 2- or 4-quadrant multiplying makes these devices a sound choice for many microprocessor-controlled gain-setting and signal-control applications. It can be operated in voltage mode, which produces a voltage output rather than a current output. Refer to the typical application information in this data sheet.

The TLC7528C is characterized for operation from 0°C to +70°C. The TLC7528I is characterized for operation from −25°C to +85°C. The TLC7528E is characterized for operation from −40°C to +85°C.

functional block diagram



operating sequence



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{DD} (to AGND or DGND) . . . . . −0.3V to 16.5V
Voltage between AGND and DGND . . . . . $\pm V_{DD}$
Input voltage range, V_I (to DGND) . . . . . −0.3V to V_{DD} + 0.3
Reference voltage, V_{refA} or V_{refB} (to AGND) . . . . . ±25V
Feedback voltage V_{RFBA} or V_{RFBB} (to AGND) . . . . . ±25V
Input voltage (voltage mode out A, out B to AGND) . . . . . −0.3V to V_{DD} + 0.3
Output voltage, V_{OA} or V_{OB} (to AGND) . . . . . ±25V
Peak input current 10µA
Operating free-air temperature range, T_A: TLC7528C . . . . . 0°C to +70°C
TLC7528I . . . . . −25°C to +85°C
TLC7528E . . . . . −40°C to +85°C
Storage temperature range, T_{stg} . . . . . −65°C to +150°C
Case temperature for 10 seconds, T_C: FN package . . . . . +260°C
Lead temperature 1,6mm (1/16 inch) from case for 10 seconds: DW or N package . . . . . +260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

package/ordering information

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

recommended operating conditions

		V_{DD} = 4.75V to 5.25V			V_{DD} = 14.5V to 15.5V			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Reference voltage, V_{refA} or V_{refB}			±10			±10		V
High-level input voltage, V_{IH}		2.4			13.5			V
Low-level input voltage, V_{IL}				0.8			1.5	V
$\overline{CS}$ setup time, $t_{su(CS)}$		50			50			ns
$\overline{CS}$ hold time, $t_{h(CS)}$		0			0			ns
DAC select setup time, $t_{su(DAC)}$		50			50			ns
DAC select hold time, $t_{h(DAC)}$		10			10			ns
Data bus input setup time $t_{su(D)}$		25			25			ns
Data bus input hold time $t_{h(D)}$		10			10			ns
Pulse duration, $\overline{WR}$ low, $t_{w(WR)}$		50			50			ns
Operating free-air temperature, T_A	TLC7628C	0		+70	0		+70	°C
	TLC7628I	−25		+85	−25		+85	
	TLC7628E	−40		+85	−40		+85	

electrical characteristics over recommended operating free-air temperature range, $V_{refA} = V_{refB} = 10V$, V_{OA} and V_{OB} at 0V (unless otherwise noted)

PARAMETER			TEST CONDITIONS	V_{DD} = 5V			V_{DD} = 15V			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
I_{IH}	High-level input current		$V_I = V_{DD}$			10			10	μA
I_{IL}	Low-level input current		$V_I = 0$	5	12	−10	5	12	−10	μA
	Reference input impedance REFA or REFB to AGND					20			20	kΩ
I_{lkg}	Output leakage current	OUTA	DAC data latch loaded with 00000000, $V_{refA} = \pm 10V$			±400			±200	nA
		OUTB	DAC data latch loaded with 00000000, $V_{refB} = \pm 10V$			±400			±200	
	Input resistance match (REFA to REFB)					±1%			±1%	
	DC supply sensitivity, $\Delta gain/\Delta V_{DD}$		$\Delta V_{DD} = \pm 10\%$			0.04			0.02	%/%
I_{DD}	Supply current (quiescent)		All digital inputs at V_{IH}min or V_{IL}max			2			2	mA
I_{DD}	Supply current (standby)		All digital inputs at 0V or V_{DD}			0.5			0.5	mA
C_i	Input capacitance	DB0−DB7				10			10	pF
		$\overline{WR}$, $\overline{CS}$, DACA/DACB				15			15	pF
C_o	Output capacitance (OUTA, OUTB)		DAC data latches loaded with 00000000			50			50	pF
			DAC data latches loaded with 11111111			120			120	

† All typical values are at T_A = +25°C.

operating characteristics over recommended operating free-air temperature range, $V_{refA} = V_{refB} = 10V$, V_{OA} and V_{OB} at 0V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{DD} = 5V			V_{DD} = 15V			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
Linearity error					±1/2			±1/2	LSB
Settling time (to 1/2LSB)		See Note 1			100			100	ns
Gain error		See Note 2			2.5			2.5	LSB
AC feedthrough	REFA to OUTA	See Note 3			−65			−65	dB
	REFB to OUTB				−65			−65	
Temperature coefficient of gain		See Note 4			0.007			0.0035	%FSR/°C
Propagation delay (from digital input to 90% of final analog output current)		See Note 5			80			80	ns
Channel-to-channel isolation	REFA to OUTB	See Note 6		77			77		dB
	REFB to OUTA	See Note 7		77			77		
Digital-to-analog glitch impulse area		Measured for code transition from 00000000 to 11111111, T_A = +25°C		160			440		nV−s
Digital crosstalk		Measured for code transition from 00000000 to 11111111, T_A = +25°C		30			60		nV−s
Harmonic distortion		V_i = 6V, f = 1kHz, T_A = +25°C		−85			−85		dB

NOTES: 1. OUTA, OUTB load = 100Ω, C_{ext} = 13pF; $\overline{WR}$ and $\overline{CS}$ at 0V; DB0−DB7 at 0V to V_{DD} or V_{DD} to 0V.
2. Gain error is measured using an internal feedback resistor. Nominal full scale range (FSR) = V_{ref} − 1LSB.
3. V_{ref} = 20V peak-to-peak, 100kHz sine wave; DAC data latches loaded with 00000000.
4. Temperature coefficient of gain measured from 0°C to +25°C or from +25°C to +70°C.
5. $V_{refA} = V_{refB}$ = 10V; OUTA/OUTB load = 100Ω, C_{ext} = 13pF; $\overline{WR}$ and $\overline{CS}$ at 0V; DB0−DB7 at 0V to V_{DD} or V_{DD} to 0V.
6. Both DAC latches loaded with 11111111; V_{refA} = 20V peak-to-peak, 100kHz sine wave; V_{refB} = 0; T_A = +25°C.
7. Both DAC latches loaded with 11111111; V_{refB} = 20V peak-to-peak, 100kHz sine wave; V_{refA} = 0; T_A = +25°C.

PRINCIPLES OF OPERATION

These devices contain two identical, 8-bit-multiplying DACs, DACA and DACB. Each DAC consists of an inverted R-2R ladder, analog switches, and input data latches. Binary-weighted currents are switched between DAC output and AGND, thus maintaining a constant current in each ladder leg independent of the switch state. Most applications require only the addition of an external operational amplifier and voltage reference. A simplified DAC circuit for DACA with all digital inputs low is shown in Figure 1.

Figure 2 shows the DACA equivalent circuit. A similar equivalent circuit can be drawn for DACB. Both DACs share the analog ground terminal 1 (AGND). With all digital inputs high, the entire reference current flows to OUTA. A small leakage current (I_{lkg}) flows across internal junctions, and as with most semiconductor devices, doubles every 10°C. C_o is due to the parallel combination of the NMOS switches and has a value that depends on the number of switches connected to the output. The range of C_o is 50pF to 120pF maximum. The equivalent output resistance (r_o) varies with the input code from 0.8R to 3R where R is the nominal value of the ladder resistor in the R-2R network.

These devices interface to a microprocessor through the data bus, $\overline{CS}$, $\overline{WR}$, and $\overline{DACA}$/DACB control signals. When $\overline{CS}$ and $\overline{WR}$ are both low, the TLC7528 analog output, specified by the $\overline{DACA}$/DACB control line, responds to the activity on the DB0−DB7 data bus inputs. In this mode, the input latches are transparent and input data directly affects the analog output. When either the $\overline{CS}$ signal or $\overline{WR}$ signal goes high, the data on the DB0−DB7 inputs are latched until the $\overline{CS}$ and $\overline{WR}$ signals go low again. When $\overline{CS}$ is high, the data inputs are disabled regardless of the state of the $\overline{WR}$ signal.

PRINCIPLES OF OPERATION

The digital inputs of these devices provide TTL compatibility when operated from a supply voltage of 5V. These devices can operate with any supply voltage in the range from 5V to 15V; however, input logic levels are not TTL-compatible above 5V.

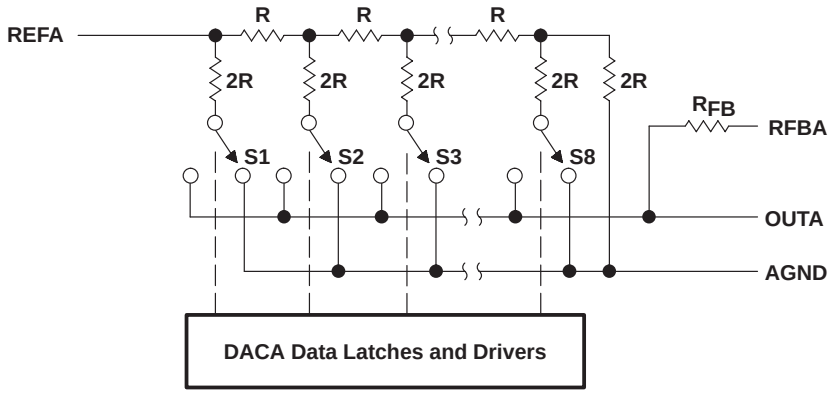


Figure 1. Simplified Functional Circuit for DACA

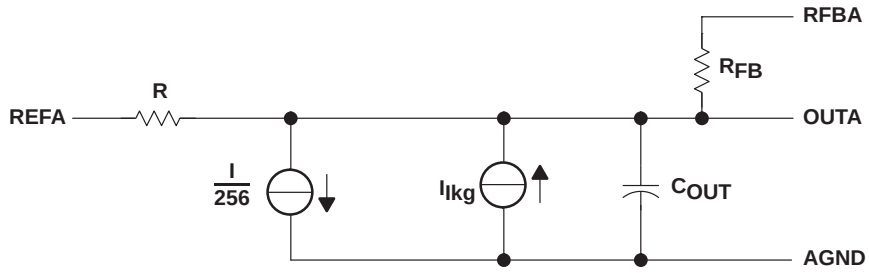


Figure 2. TLC7528 Equivalent Circuit, DACA Latch Loaded With 11111111

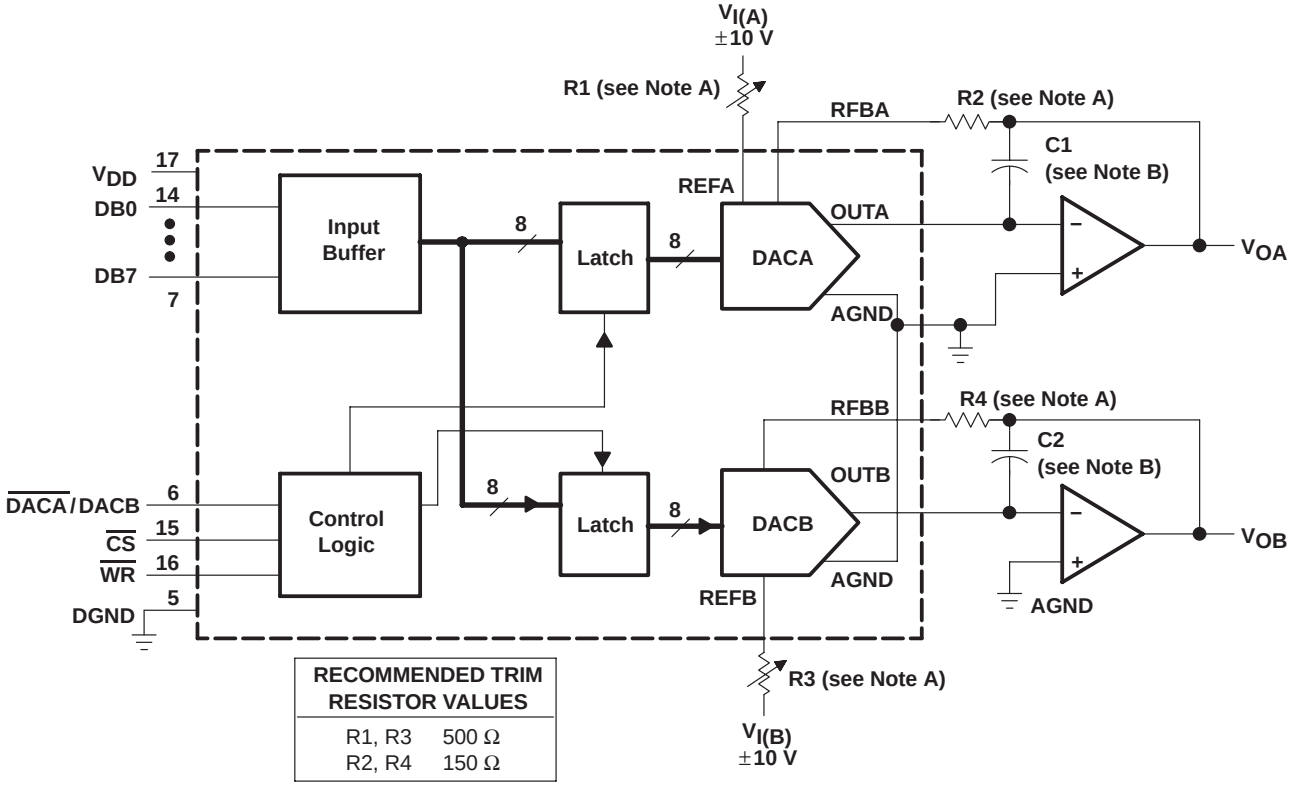
MODE SELECTION TABLE

$\overline{DACA}$/DACB	$\overline{CS}$	$\overline{WR}$	DACA	DACB
L	L	L	Write	Hold
H	L	L	Hold	Write
X	H	X	Hold	Hold
X	X	H	Hold	Hold

L = low level, H = high level, X = don't care

APPLICATION INFORMATION

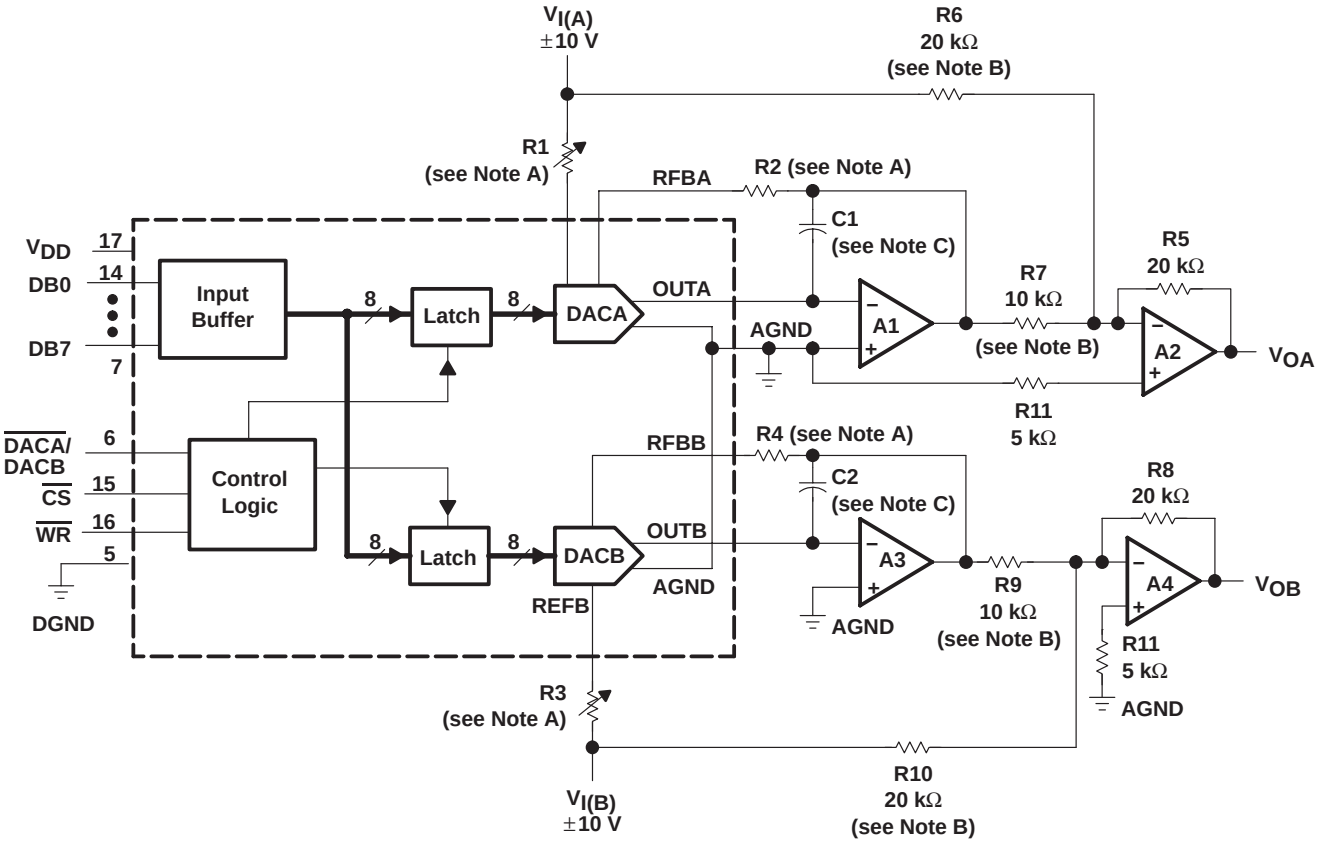
These devices are capable of performing 2-quadrant or full 4-quadrant multiplication. Circuit configurations for 2-quadrant and 4-quadrant multiplication are shown in Figure 3 and Figure 4. Table 1 and Table 2 summarize input coding for unipolar and bipolar operation, respectively.



NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table for recommended values. Make gain adjustment with digital input of 255.
B. C1 and C2 phase compensation capacitors (10pF to 15pF) are required when using high-speed amplifiers to prevent ringing or oscillation.

Figure 3. Unipolar Operation (2-Quadrant Multiplication)

APPLICATION INFORMATION



NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table in Figure 3 for recommended values. Adjust R1 for V_{OA} = 0V with code 10000000 in DACA latch. Adjust R3 for V_{OB} = 0V with 10000000 in DACB latch.
B. Matching and tracking are essential for resistor pairs R6, R7, R9, and R10.
C. C1 and C2 phase compensation capacitors (10pF to 15pF) may be required if A1 and A3 are high-speed amplifiers.

Figure 4. Bipolar Operation (4-Quadrant Operation)

Table 1. Unipolar Binary Code

DAC LATCH CONTENTS MSB LSB†	ANALOG OUTPUT
1 1 1 1 1 1 1 1	$-V_I$ (255/256)
1 0 0 0 0 0 0 1	$-V_I$ (129/256)
1 0 0 0 0 0 0 0	$-V_I$ (128/256) = $-V_I/2$
0 1 1 1 1 1 1 1	$-V_I$ (127/256)
0 0 0 0 0 0 0 1	$-V_I$ (1/256)
0 0 0 0 0 0 0 0	$-V_I$ (0/256) = 0

† 1LSB = $(2^{-8})V_I$

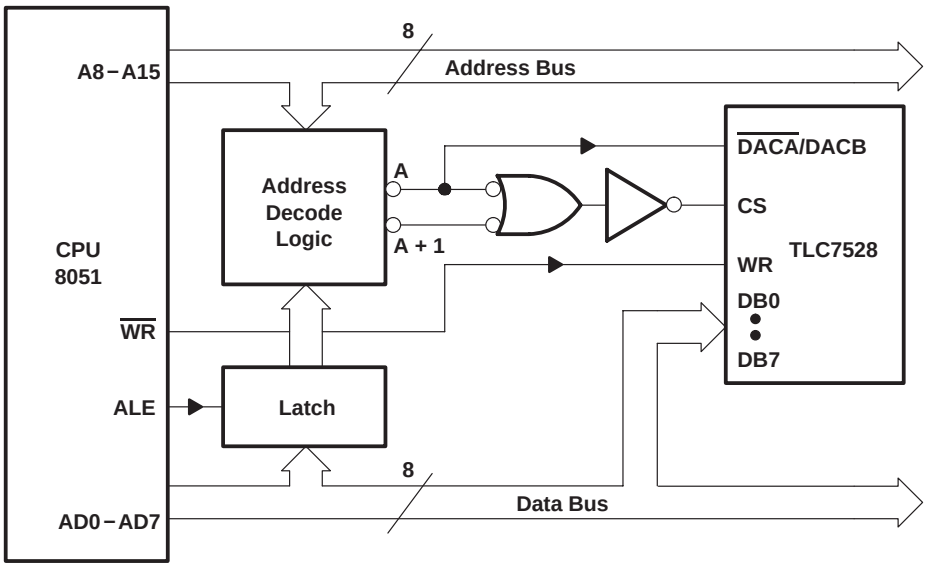
Table 2. Bipolar (Offset Binary) Code

DAC LATCH CONTENTS MSB LSB‡	ANALOG OUTPUT
1 1 1 1 1 1 1 1	V_I (127/128)
1 0 0 0 0 0 0 1	V_I (1/128)
1 0 0 0 0 0 0 0	0V
0 1 1 1 1 1 1 1	$-V_I$ (1/128)
0 0 0 0 0 0 0 1	$-V_I$ (127/128)
0 0 0 0 0 0 0 0	$-V_I$ (128/128)

‡ 1LSB = $(2^{-7})V_I$

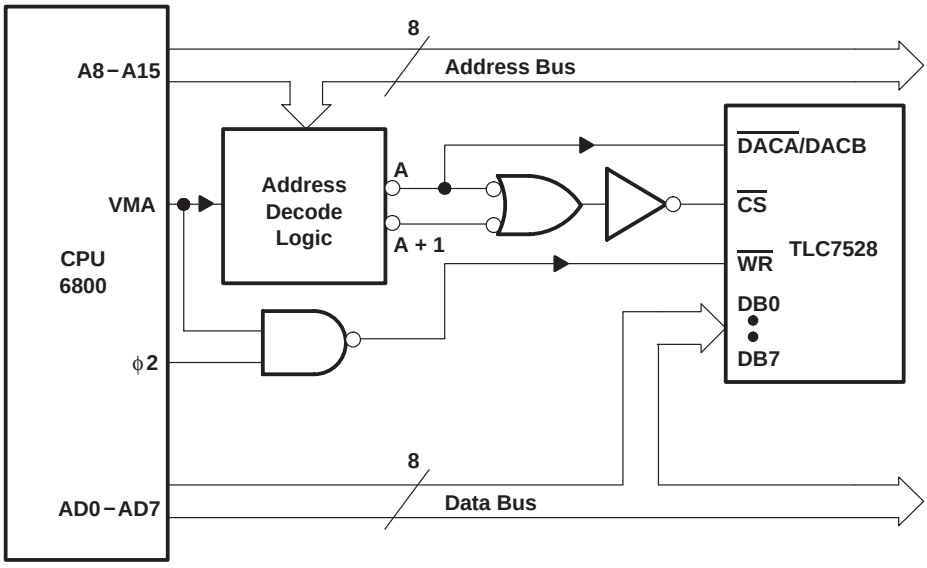
APPLICATION INFORMATION

microprocessor interface information



NOTE A: A = decoded address for TLC7528 DACA
A + 1 = decoded address for TLC7528 DACB

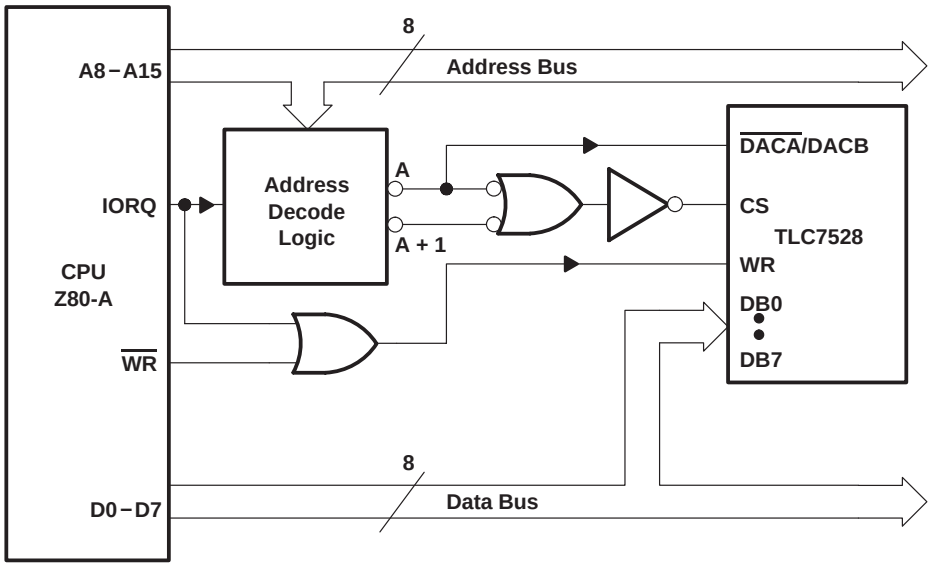
Figure 5. TLC7528: Intel 8051 Interface



NOTE A: A = decoded address for TLC7528 DACA
A + 1 = decoded address for TLC7528 DACB

Figure 6. TLC7528: 6800 Interface

APPLICATION INFORMATION



NOTE A: A = decoded address for TLC7528 DACA
A + 1 = decoded address for TLC7528 DACB

Figure 7. TLC7528 To Z-80A Interface

programmable window detector

The programmable window comparator shown in Figure 8 determines if the voltage applied to the DAC feedback resistors is within the limits programmed into the data latches of these devices. Input signal range depends on the reference and polarity; that is, the test input range is 0 to $-V_{ref}$. The DACA and DACB data latches are programmed with the upper and lower test limits. A signal within the programmed limits drives the output high.

APPLICATION INFORMATION

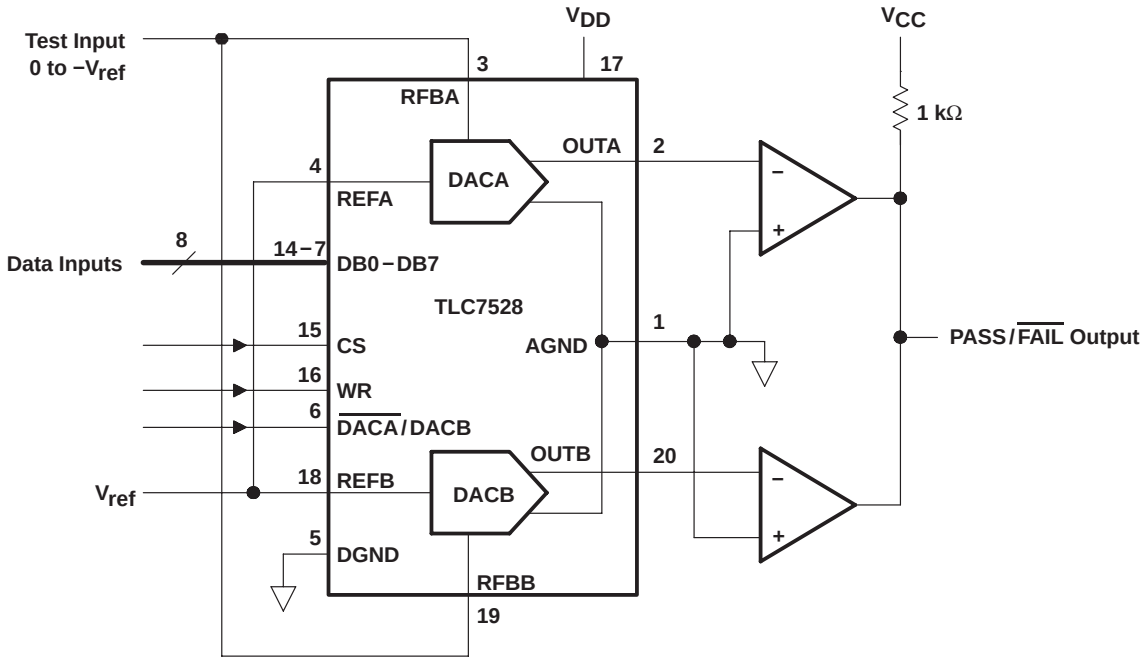


Figure 8. Digitally-Programmable Window Comparator (Upper- and Lower-Limit Tester)

digitally-controlled signal attenuator

Figure 9 shows a TLC7528 configured as a two-channel programmable attenuator. Applications include stereo audio and telephone signal level control. Table 3 shows input codes vs attenuation for a 0dB to 15.5dB range.

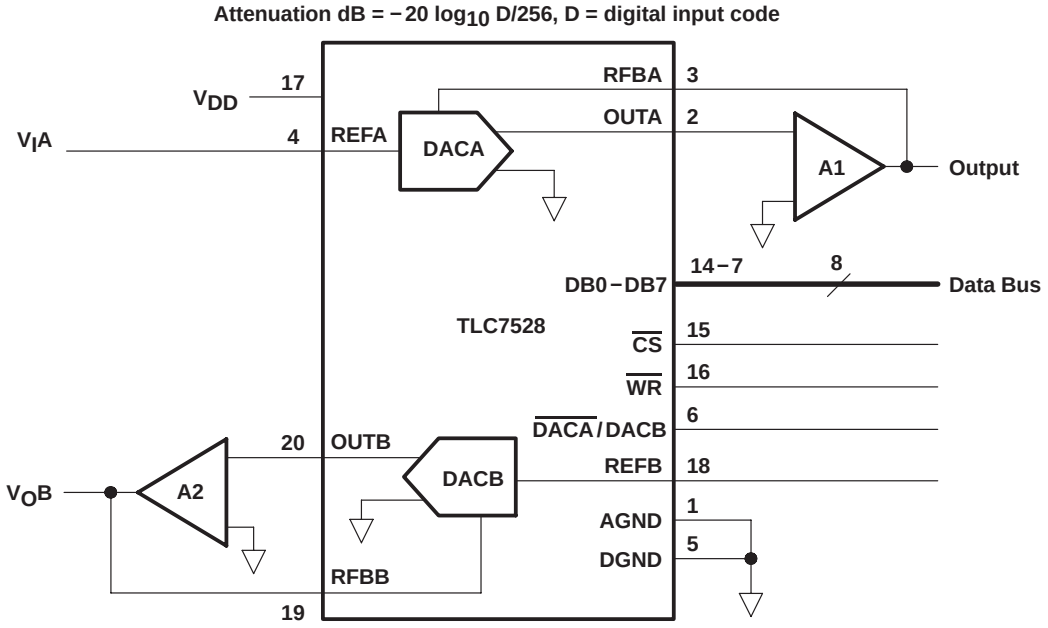


Figure 9. Digitally Controlled Dual Telephone Attenuator

APPLICATION INFORMATION

Table 3. Attenuation vs DACA, DACB Code

ATTEN (dB)	DAC INPUT CODE	CODE IN DECIMAL	ATTN (dB)	DAC INPUT CODE	CODE IN DECIMAL
0	1 1 1 1 1 1 1 1	255	8.0	0 1 1 0 0 1 1 0	102
0.5	1 1 1 1 0 0 1 0	242	8.5	0 1 1 0 0 0 0 0	96
1.0	1 1 1 0 0 1 0 0	228	9.0	0 1 0 1 1 0 1 1	91
1.5	1 1 0 1 0 1 1 1	215	9.5	0 1 0 1 0 1 1 0	86
2.0	1 1 0 0 1 0 1 1	203	10.0	0 1 0 1 0 0 0 1	81
2.5	1 1 0 0 0 0 0 0	192	10.5	0 1 0 0 1 1 0 0	76
3.0	1 0 1 1 0 1 0 1	181	11.0	0 1 0 0 1 0 0 0	72
3.5	1 0 1 0 1 0 1 1	171	11.5	0 1 0 0 0 1 0 0	68
4.0	1 0 1 0 0 0 1 0	162	12.0	0 1 0 0 0 0 0 0	64
4.5	1 0 0 1 1 0 0 0	152	12.5	0 0 1 1 1 1 0 1	61
5.0	1 0 0 1 1 1 1 1	144	13.0	0 0 1 1 1 0 0 1	57
5.5	1 0 0 0 1 0 0 0	136	13.5	0 0 1 1 0 1 1 0	54
6.0	1 0 0 0 0 0 0 0	128	14.0	0 0 1 1 0 0 1 1	51
6.5	0 1 1 1 1 0 0 1	121	14.5	0 0 1 1 0 0 0 0	48
7.0	0 1 1 1 0 0 1 0	114	15.0	0 0 1 0 1 1 1 0	46
7.5	0 1 1 0 1 1 0 0	108	15.5	0 0 1 0 1 0 1 1	43

programmable state-variable filter

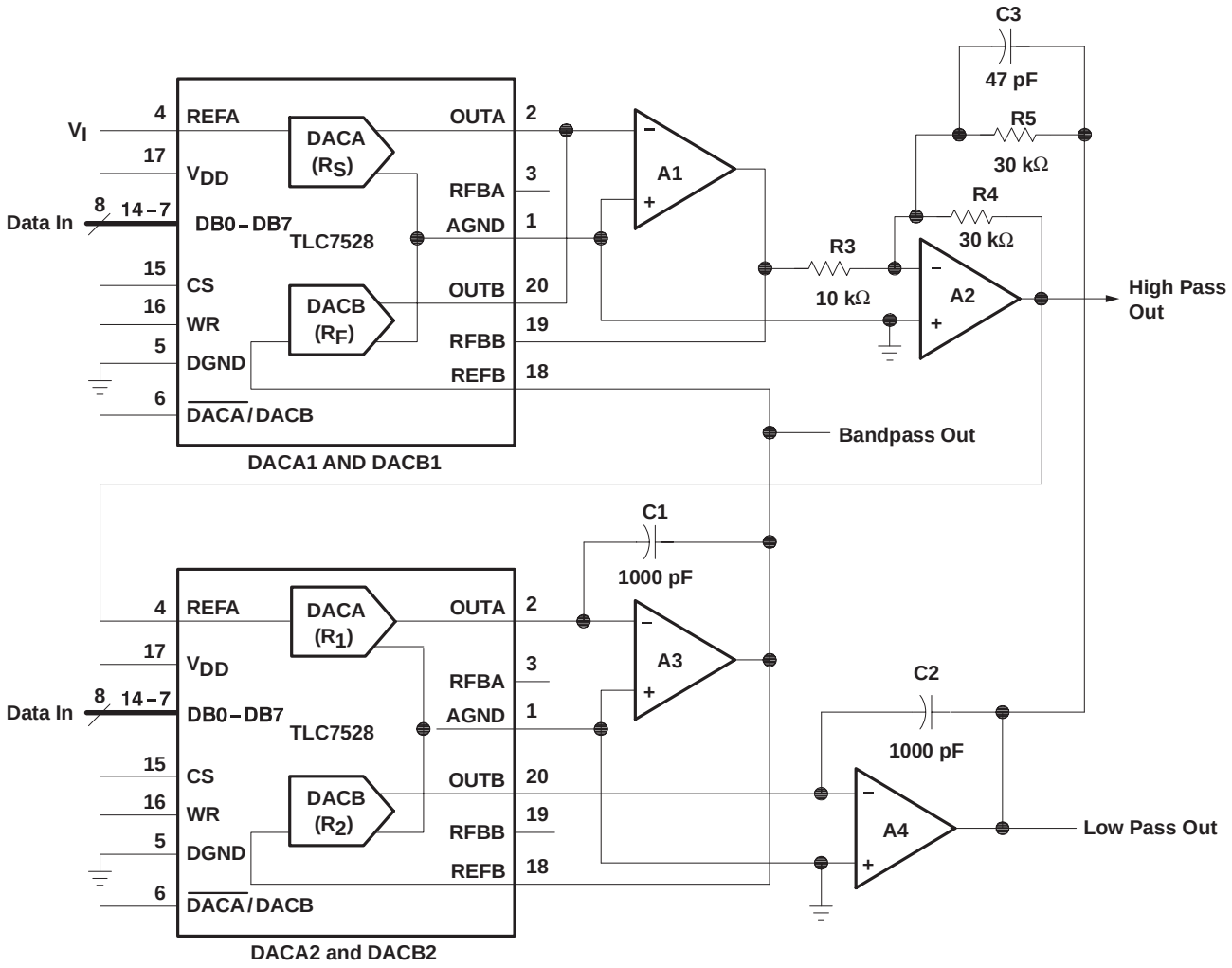
This programmable state-variable or universal filter configuration provides low-pass, high-pass, and bandpass outputs, and is suitable for applications requiring microprocessor control of filter parameters.

As shown in Figure 10, DACA1 and DACB1 control the gain and Q of the filter while DACA2 and DACB2 control the cutoff frequency. Both halves of the DACA2 and DACB2 must track accurately in order for the cutoff-frequency equation to be true. With the TLC7528, this validity is easy to achieve.

$$f_C = \frac{1}{2\pi R1C1}$$

The programmable range for the cutoff or center frequency is 0kHz to 15kHz with a Q ranging from 0.3 to 4.5. This parameter defines the limits of the component values.

APPLICATION INFORMATION



Circuit Equations:

$C_1 = C_2$, $R_1 = R_2$, $R_4 = R_5$

$$Q = \frac{R_3}{R_4} \times \frac{R_F}{R_{fb(DACB1)}}$$

Where:

R_{fb} **is the internal resistor connected between OUTB and RFBB**

$$G = -\frac{R_F}{R_S}$$

NOTES: A. Op-amps A1, A2, A3, and A4 are TL287.
B. $\overline{CS}$ compensates for the op-amp gain-bandwidth limitations.
C. DAC equivalent resistance equals $\frac{256 \times \text{(DAC ladder resistance)}}{\text{DAC digital code}}$

Figure 10. Digitally-Controlled State-Variable Filter

APPLICATION INFORMATION

voltage-mode operation

It is possible to operate the current multiplying D/A converter of these devices in a voltage mode. In the voltage mode, a fixed voltage is placed on the current output terminal. The analog output voltage is then available at the reference voltage terminal. Figure 11 is an example of a current multiplying D/A that operates in the voltage mode.

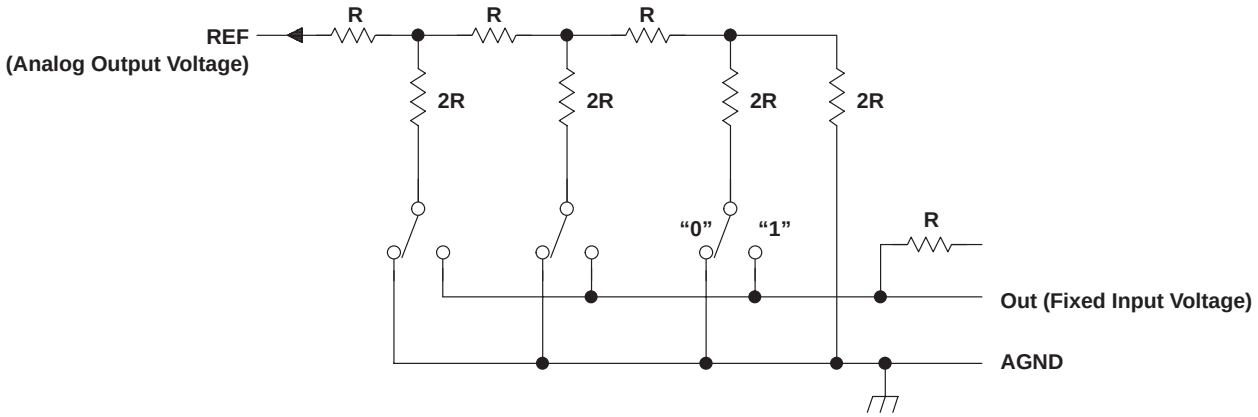


Figure 11. Voltage-Mode Operation

The following equation shows the relationship between the fixed input voltage and the analog output voltage:

$$V_O = V_I (D/256)$$

Where:

V_O = analog output voltage
V_I = fixed input voltage (must not be forced below 0V.)
D = digital input code converted to decimal

In voltage-mode operation, these devices meet the following specification:

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Linearity error at REFA or REFB	V_{DD} = 5V, OUTA or OUTB at 2.5V, T_A = +25°C		1	LSB

Revision History

DATE	REV	PAGE	SECTION	DESCRIPTION
11/08	E	13	Application Information	Corrected Figure 10.
6/07	D	Front Page	—	Deleted Available Options table.
		3	—	Inserted Package/Ordering information.

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLC7528CDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C	Samples
TLC7528CDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C	Samples
TLC7528CDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C	Samples
TLC7528CFN	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	TLC7528C	Samples
TLC7528CFNG3	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	TLC7528C	Samples
TLC7528CFNR	ACTIVE	PLCC	FN	20	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	TLC7528C	Samples
TLC7528CN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TLC7528CN	Samples
TLC7528CNS	ACTIVE	SO	NS	20	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528	Samples
TLC7528CNSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528	Samples
TLC7528CPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C	Samples
TLC7528CPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TLC7528C	Samples
TLC7528EDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528E	Samples
TLC7528EDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528E	Samples
TLC7528EDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLC7528E	Samples
TLC7528EN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TLC7528EN	Samples
TLC7528IDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I	Samples
TLC7528IDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLC7528IDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I	Samples
TLC7528IFN	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-25 to 85	TLC7528I	Samples
TLC7528IFNG3	ACTIVE	PLCC	FN	20	46	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-25 to 85	TLC7528I	Samples
TLC7528IN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-25 to 85	TLC7528IN	Samples
TLC7528IPW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I	Samples
TLC7528IPWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I	Samples
TLC7528IPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	TLC7528I	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

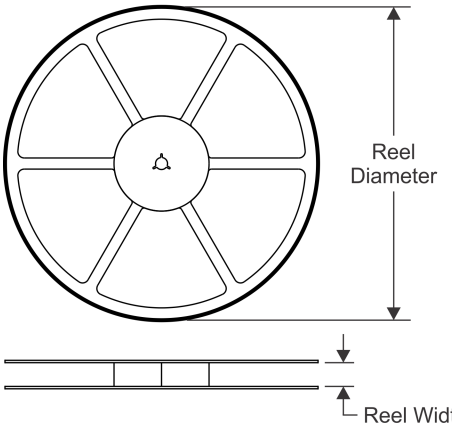
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

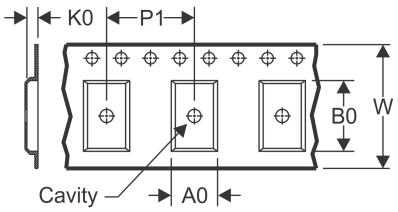
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

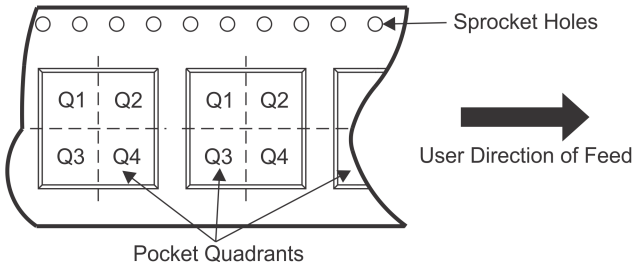


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

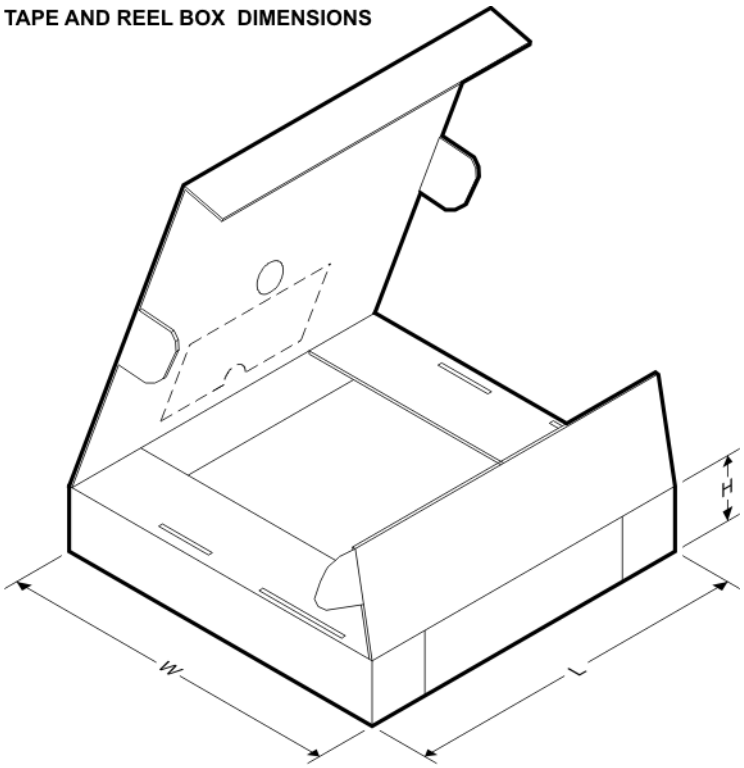
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC7528CNSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
TLC7528EDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
TLC7528IDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
TLC7528IPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



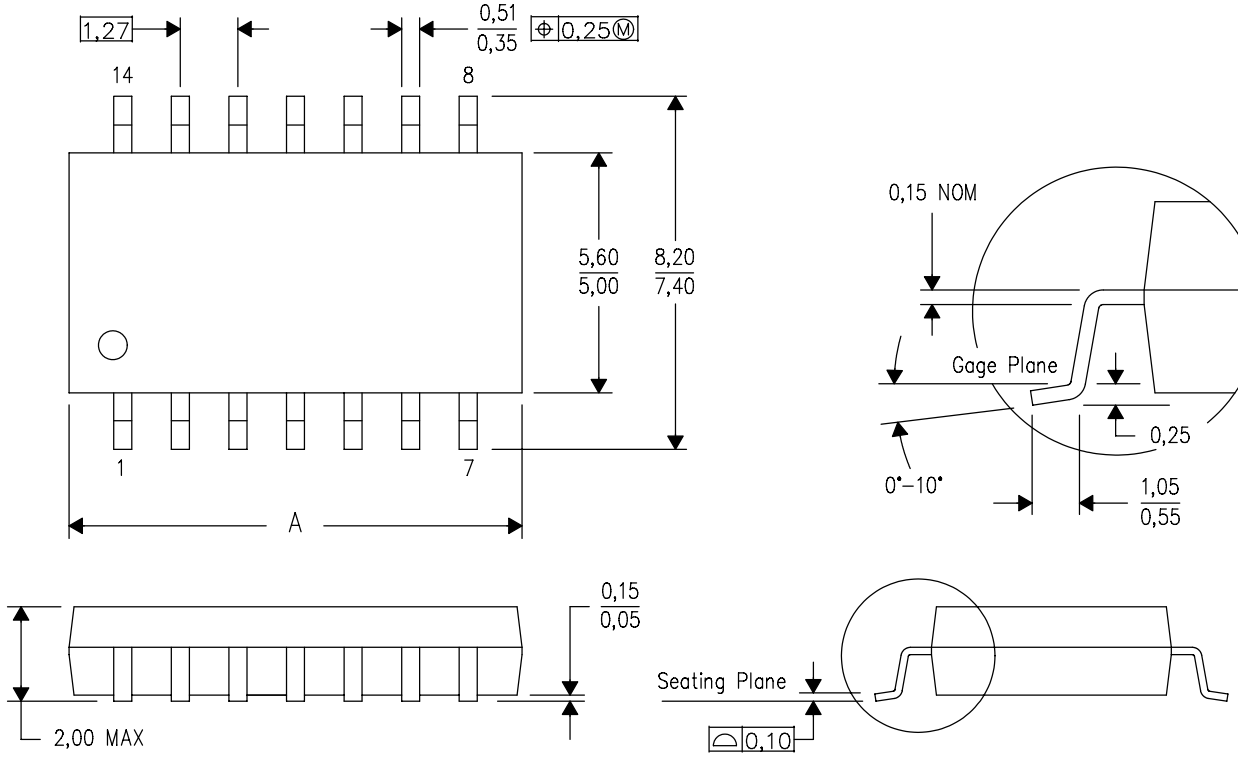
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC7528CNSR	SO	NS	20	2000	367.0	367.0	45.0
TLC7528EDWR	SOIC	DW	20	2000	367.0	367.0	45.0
TLC7528IDWR	SOIC	DW	20	2000	367.0	367.0	45.0
TLC7528IPWR	TSSOP	PW	20	2000	367.0	367.0	38.0

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN

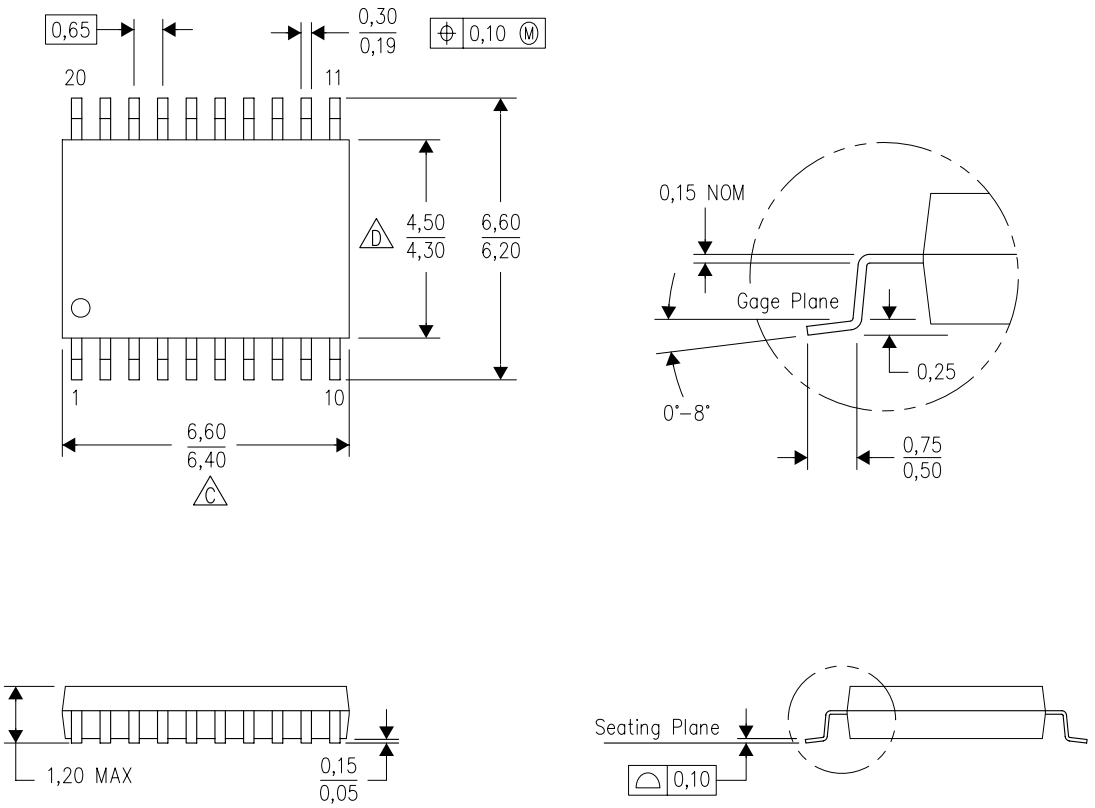


DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

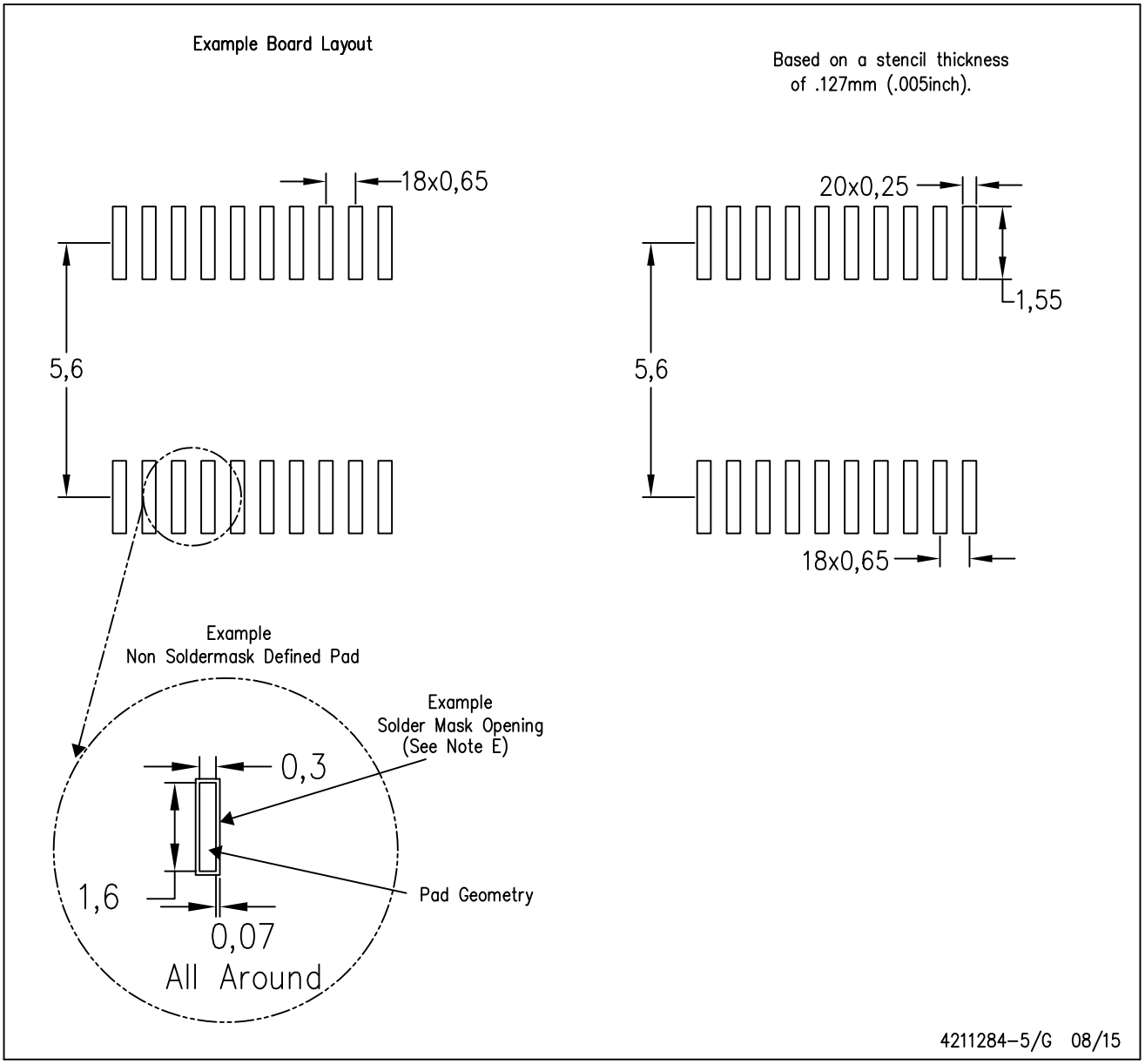
PW (R–PDSO–G20) PLASTIC SMALL OUTLINE



4040064–5/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G20) PLASTIC SMALL OUTLINE

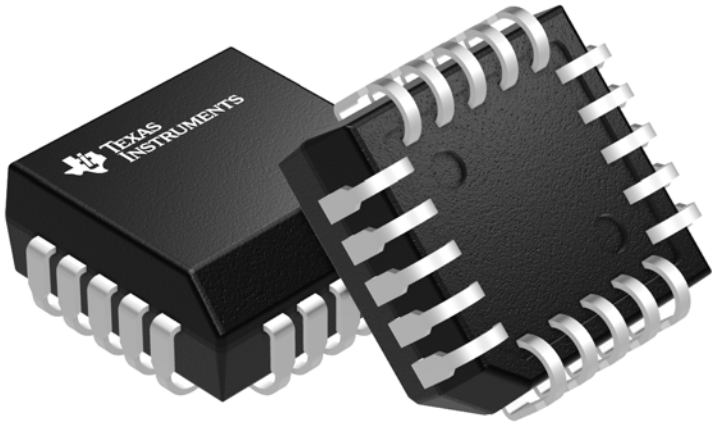


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

GENERIC PACKAGE VIEW

FN 20 PLCC - 4.57 mm max height

PLASTIC CHIP CARRIER



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

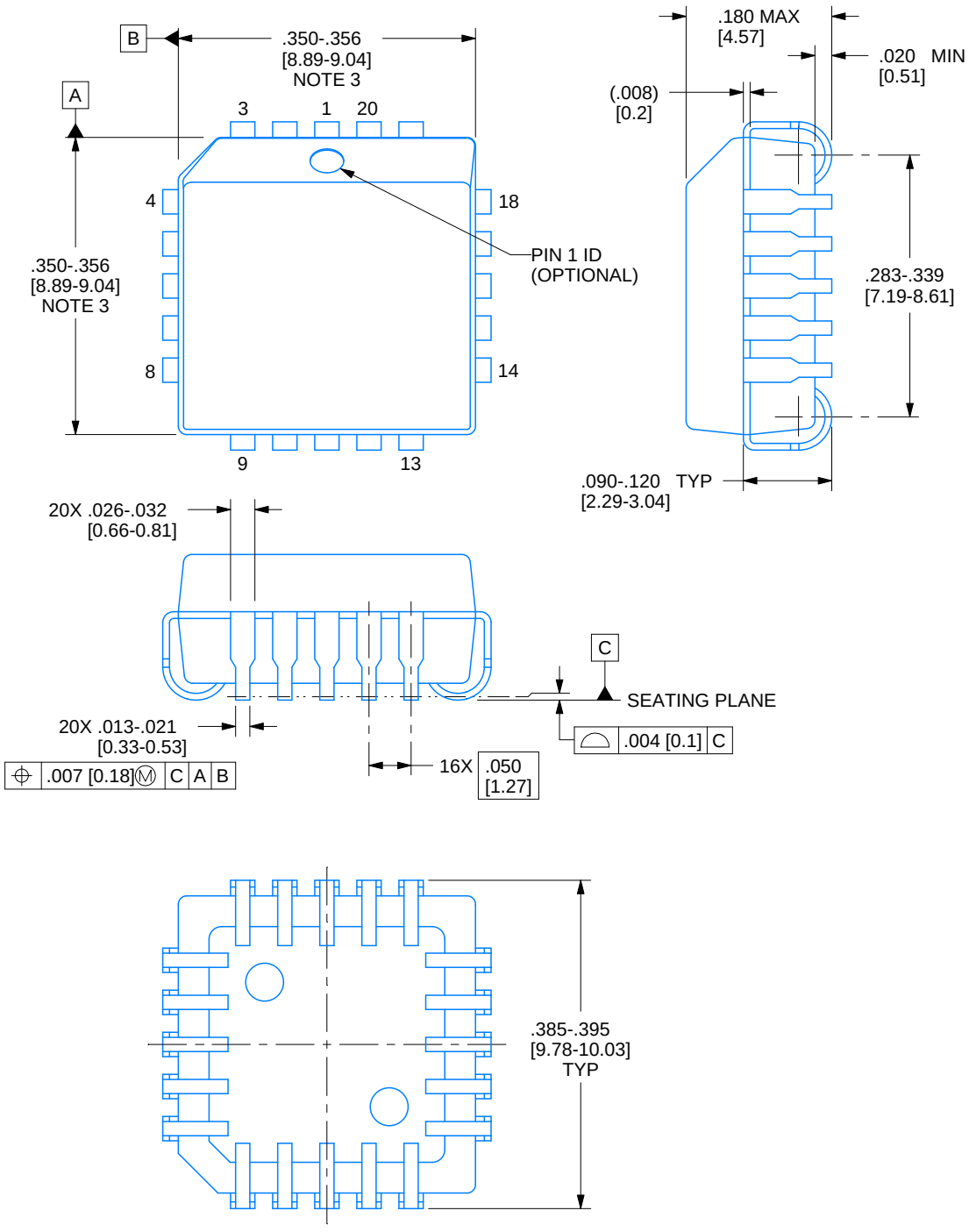
4040005-2/C

PACKAGE OUTLINE

FN0020A

PLCC - 4.57 mm max height

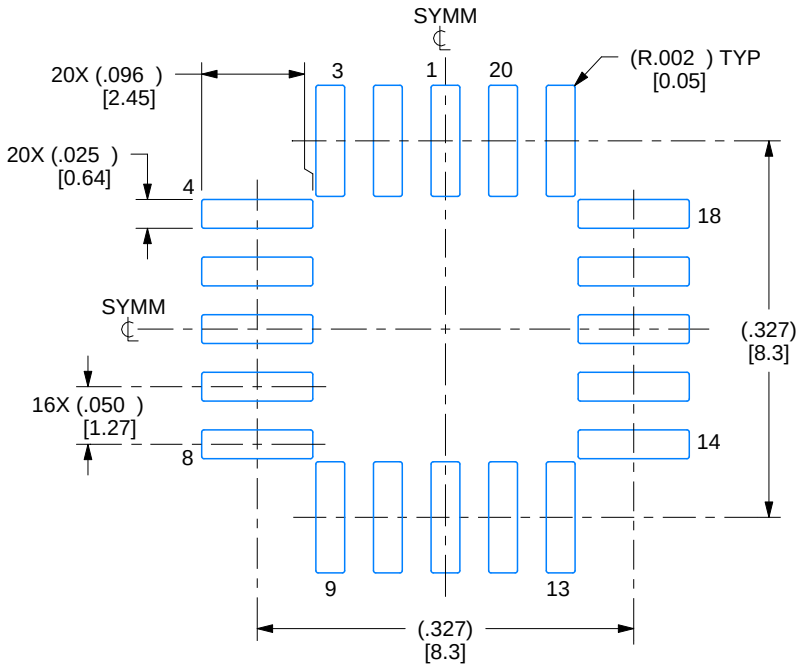
PLASTIC CHIP CARRIER



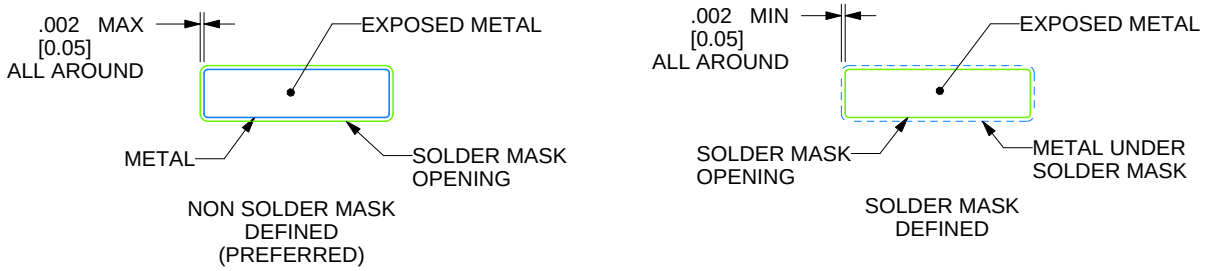
4215152/B 04/2017

NOTES:

1. All linear dimensions are in inches. Any dimensions in brackets are in millimeters. Any dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Dimension does not include mold protrusion. Maximum allowable mold protrusion .01 in [0.25 mm] per side.
4. Reference JEDEC registration MS-018.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:6X

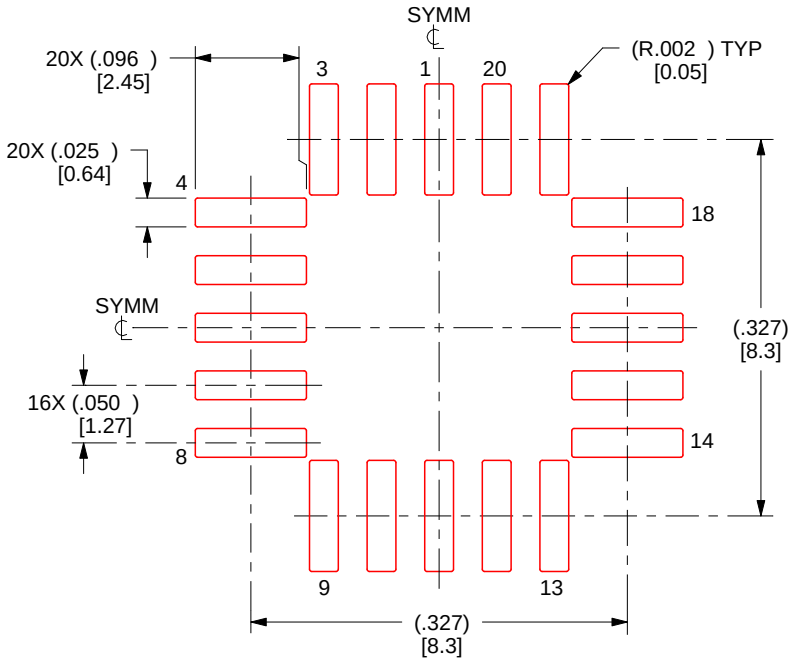


SOLDER MASK DETAILS

4215152/B 04/2017

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4215152/B 04/2017

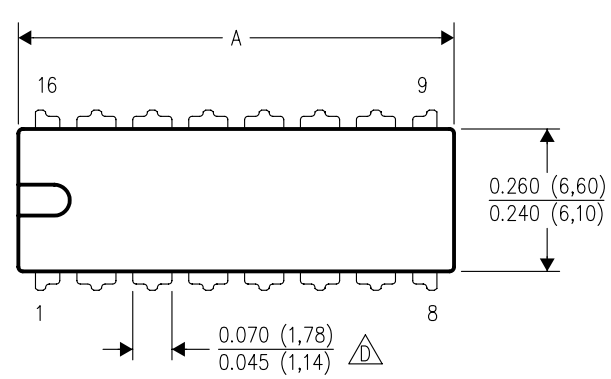
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

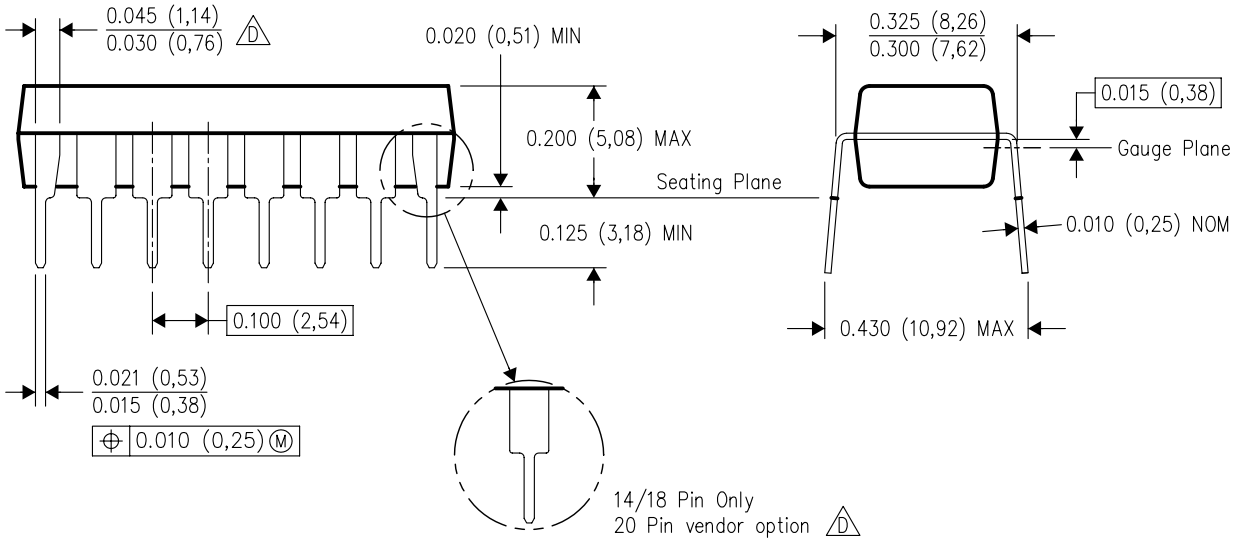
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

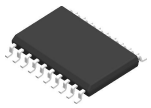


DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

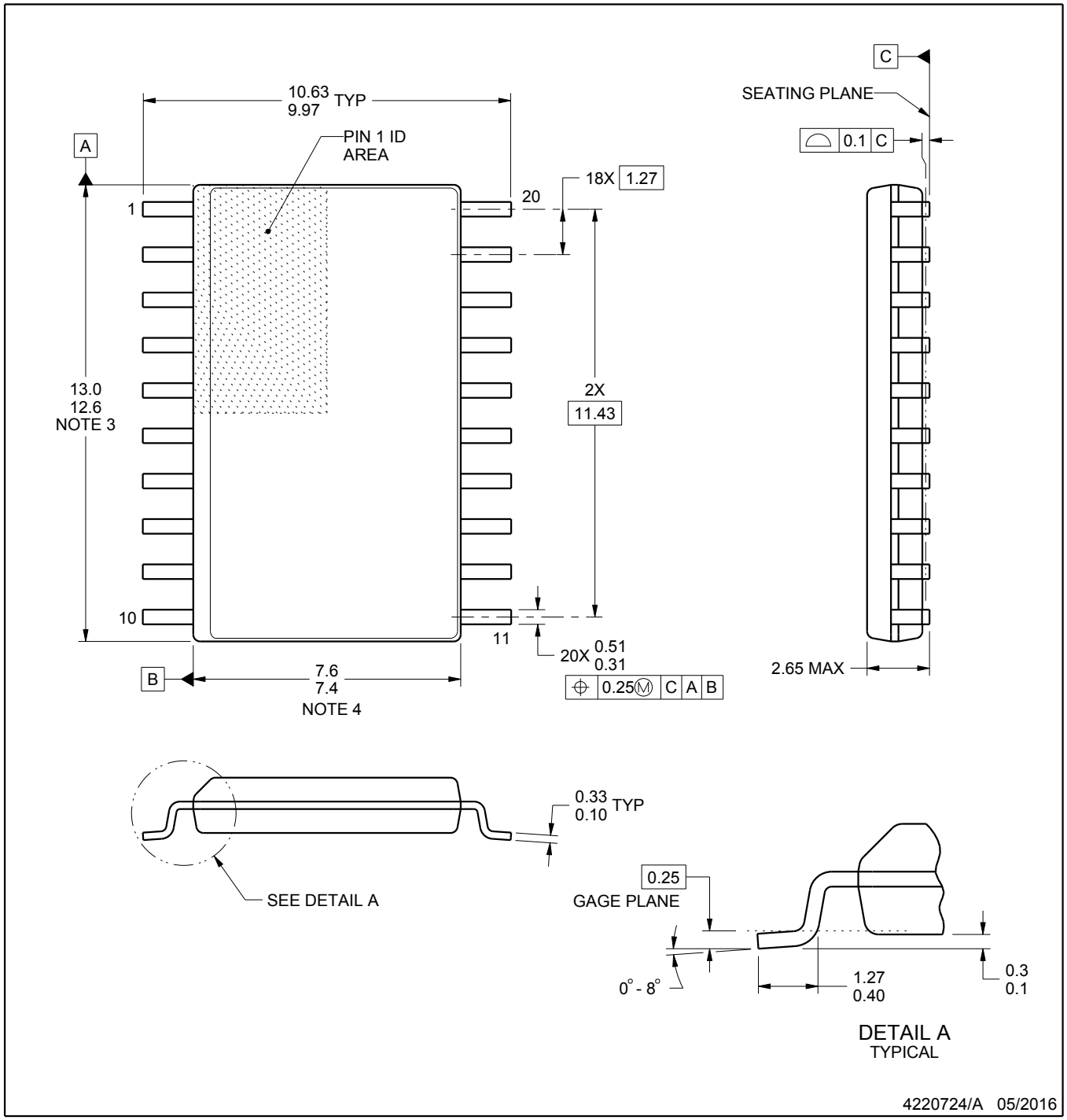


PACKAGE OUTLINE

DW0020A

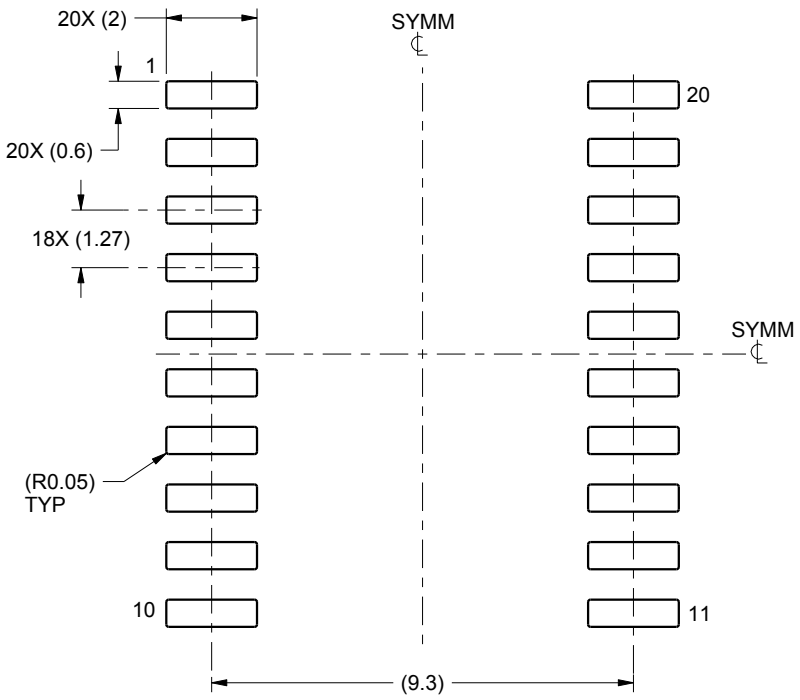
SOIC - 2.65 mm max height

SOIC

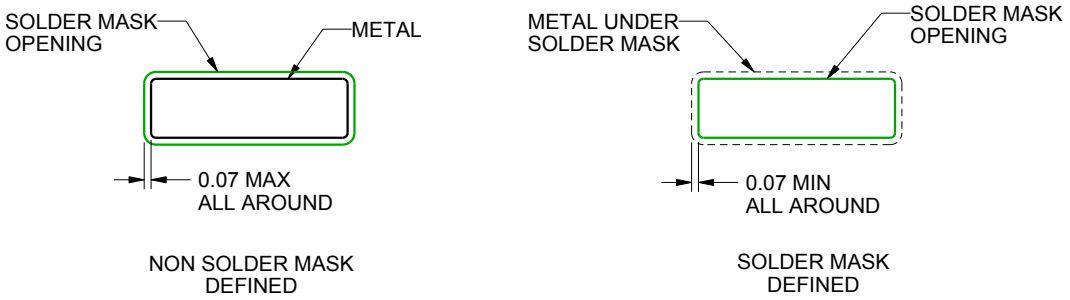


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:6X

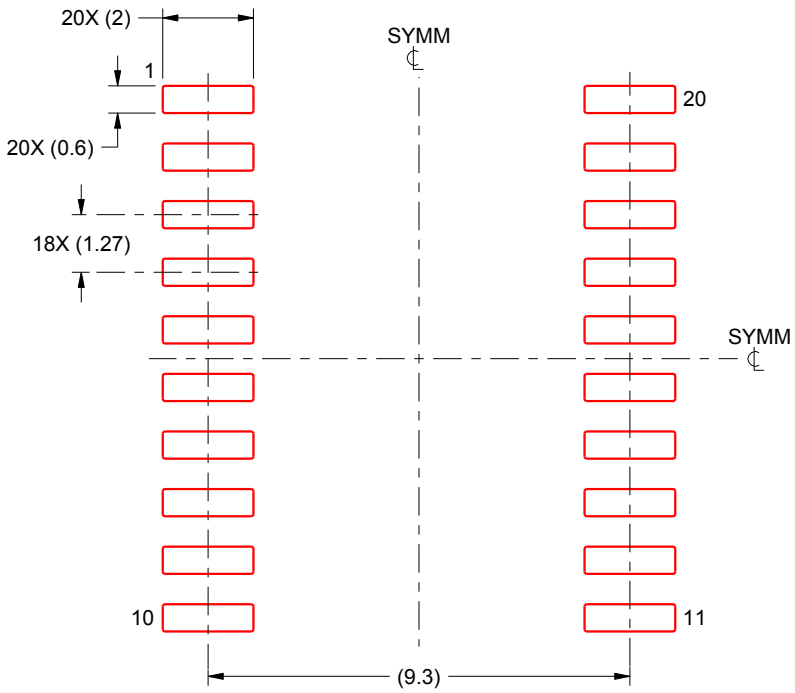


SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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